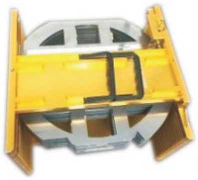
ACA
ACA VISION TECHNOLOGY



QFN Top & Bottom on Wafer Ring Inspection Handler

2 Cameras Top & Bottom

AQN2D2

Specification	Description	
Machine Dimension	1600mm(L) x 800mm(D) x 1520mm(H)	
Weight	1,000kg	
Input Voltage	230 VAC 50/60 Hz Single phase	
Working Air Pressure	0.5 MPa	
Machine Controller	PLC / PC Based	
Handling Mechanism	XY Table Indexing	
UPH	50k for 1mm x 1mm Package	
Communication	IO, Serial Port, Ethernet	
Vision Inspection Capabilities	Camera Resolution	4M
	FOV	18mm x 18mm
	Pixel Resolution	0.009mm/pixel
	Total Cycle Time	300ms ~ 400ms
	GR&R	< 10%
	Minimum Detectable	3 mils x 3 mils
	Accuracy	+/- 0.5mils

Features

- Result mapping, report and defect grouping
- Accumulative data/lot report, SPC and GRR report
- Barcode scanning
- Support miscellaneous communication protocols
- Machine interlock and sensor control for product protection
- Support multiple lead frame type and easy conversion
- Eject NG unit treatment upon defect detection
- Servo motor with encoder for precise wire cutting
- Smart instant responses for various states
- Eject the NG unit to Bin
- Checking Criteria : Chipping, Contam on Lead, Contam on Solder Mask, Damaged Terminal, Expose D/A, Expose Die, Expose Dot, Expose Glue. Expose Line, Incomplete Mold, L/F defect, Mold Flash, Resin Bleed, Over Etching, Scratches on Terminal, Terminal Burr, Under Etching, Void, Pin Hole, Marking

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Post Wire Bond Inspection Machine – Single Shutter

Specification	Description	
Machine Dimension	1610mm(L) x 630mm(D) x 1620mm(H)	
Weight	800kg	
Input Voltage	230 VAC 50/60 Hz Single phase	
Working Air Pressure	0.5 MPa	
Machine Controller	PLC Based	
Handling Mechanism	XY Table Indexing	
UPH	5k	
Communication	IO, Serial Port, Ethernet	
Vision Inspection Capabilities	Camera Resolution	2448 x 2048
	FOV	12mm x 10mm
	Pixel Resolution	0.005mm/pixel
	Total Cycle Time	350ms
	GR&R	< 10%
	Minimum Detectable	2 mils x 2mils
	Accuracy	+/- 0.5mils

Features

- Result mapping, report and defect grouping
- Accumulative data/lot report, SPC and GRR report
- Barcode scanning
- Support miscellaneous communication protocols
- Machine interlock and sensor control for product protection
- Support multiple lead frame type and easy conversion
- Wire treatment upon defect detection
- Servo motor with encoder for precise wire cutting
- Post wire cutting inspection after wire treatment
- Smart instant responses for various states

Post Wire Bond Inspection Machine – Double Shutter

Specification	Description	
Machine Dimension	2180mm(L) x 1000mm(D) x 1640mm(H)	
Weight	1,200kg	
Input Voltage	230 VAC 50/60 Hz Single phase	
Working Air Pressure	0.5 Mpa	
Machine Controller	PLC Based	
Handling Mechanism	XY Table Indexing	
UPH	8k	
Communication	IO, Serial Port, Ethernet	
Vision Inspection Capabilities	Camera Resolution	3296 x 2472
	FOV	11.5mm x 8.6mm
	Pixel Resolution	0.003mm/pixel
	Total Cycle Time	350ms
	GR&R	< 10%
	Minimum Detectable	2 mils x 2mils
	Accuracy	+/- 0.5mils

Features

- Result mapping, report and defect grouping
- Accumulative data/lot report, SPC and GRR report
- Barcode scanning
- Support miscellaneous communication protocols
- Machine interlock and sensor control for product protection
- Support multiple lead frame type and easy conversion
- Wire treatment upon defect detection
- Servo motor with encoder for precise wire cutting
- Post wire cutting inspection after wire treatment
- Smart instant responses for various states